

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	736	29/890.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:59
S2	1977	347/56,70,71,73.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 07:56
S3	73856	(pressure with (room cavity chamber)) with (layer plate laminate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:04
S4	0	S1 same S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 07:58
S5	0	S1 with S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 07:58
S6	117	S1 and S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 07:58
S7	39	S3 and S6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 07:59
S8	14611	((forg\$3 work\$3 ductile) with (metal)) same (dent impression groove punch)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:01

S9	214	S3 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:01
S10	1498	((forg\$3 work\$3 ductile) with (metal)) same (dent impression groove punch) same (stress strain)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:01
S11	32	S3 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:01
S12	0	("2004/0107759").URPN.	USPAT	OR	ON	2005/03/31 08:04
S13	630	(pressure with (room cavity chamber)) with (layer plate laminate) with (stress strain)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:05
S14	29	S2 and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:04
S15	21	(pressure with (room cavity chamber)) with (layer plate laminate) with (stress strain) with (dent impression groove impression pit indentation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:07
S16	48	(pressure with (room cavity chamber)) with (layer plate laminate) with (stress strain) same (dent impression groove impression pit indentation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:07
S17	242	(pressure with (room cavity chamber)) with (layer plate laminate) same (stress strain) same (dent impression groove impression pit indentation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:13

S18	4	S2 and S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:11
S19	2	"20040112109"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:12
S20	10	S2 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:15
S21	1	S1 and S2 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:15
S22	3	S1 and S8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:16
S23	60952	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:16
S24	32	S8 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:16
S25	22	("3747120" "3988745" "4216477" "4266232" "4312010" "4367479" "4367480" "4435721" "4455560" "4460906" "4521788" "4525728" "4528575" "4584590" "4599628" "4605939" "4635079" "4665409" "4680595" "4727378" "4835554" "4947184").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/31 08:20
S26	49	("5087930").URPN.	USPAT	OR	ON	2005/03/31 08:26

S27	25403	(pressure with (room cavity chamber)) with (dent impression groove impression pit indentation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:42
S28	463	S23 and S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:41
S29	4527079	planar flat parallel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:41
S30	331	S28 and S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:42
S31	1537	(pressure with (room cavity chamber)) with (dent impression pit indentation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:56
S32	20	S23 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:43
S33	7	("4047184" "4216477" "4312008" "4600934" "4999650" "5096535" "5471232").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/03/31 08:49
S34	7	("5956058").URPN.	USPAT	OR	ON	2005/03/31 08:50
S35	226	((pressure with (room cavity chamber)) with (dent impression pit indentation)) same (planar flat parallel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:59
S36	3	S35 and S23	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 08:58

S37	6359	(pressure with (room cavity chamber)) with (stress strain)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:20
S38	125	S23 and S37	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:00
S39	403153	(pressure with (room cavity chamber plate)) with (nozzle (layer plate laminate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:21
S40	44533	((pressure with (room cavity chamber plate)) with (nozzle (layer plate laminate))) same (cte warp\$3 flat\$2 coplanar dent)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:24
S41	562	S23 and S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:22
S42	17151	((pressure with (room cavity chamber plate)) with (nozzle (layer plate laminate))) with (cte warp\$3 flat\$2 coplanar dent)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:25
S43	363	S23 and S42	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:24
S44	16991	((pressure with (room cavity chamber plate)) with (nozzle (layer plate laminate))) with (warp\$3 flat\$2 coplanar)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:25

S45	362	S23 and S44	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:25
S46	87	S2 and S44	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:25
S47	736	29/890.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:47
S48	1977	347/56,70,71,73.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:28
S49	60952	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:29
S50	10453	((cavity room chamber) with (form\$3 work\$3 roll\$3)) with (nozzle with (plate layer metal))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:31
S51	550	S48 and S50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:31
S52	906	((cavity room chamber) with (form\$3 work\$3 roll\$3)) with (nozzle with (plate layer metal)) with (flat parallel warp\$3 coplaner alignment)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:32

S53	55	S48 and S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:42
S54	37068	(nickle metal\$3 ductl\$3) with ((nozzle chamber) with (plate layer substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:45
S55	1289	S49 and S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:45
S56	79	(nickle metal\$3 ductl\$3) with ((nozzle chamber) with (plate layer substrate)) with (dent indentation pit knurl)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:47
S57	1	S49 and S56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:47
S58	0	S47 and S56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:47
S59	237	S47 and ink\$2jet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:47
S60	1217815	(nickle metal\$3 ductl\$3) with (plate layer substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:48

S61	1257	((nickle metal\$3 duct\$3) with (plate layer substrate)) with ink\$3jet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:48
S62	383	S49 and S61	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:49
S63	32	S47 and S61	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 09:49
S64	2964	347/68-73.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:12
S65	40	(pressure near4 (plate layer laminate)) with (nozzle near4 (plate layer laminate)) with alignment	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:17
S66	8256	(pressure near4 (plate layer laminate)) with (dent impression (blind near2 hole) depression via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:19
S67	109	S64 and S66	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:18
S68	3320	((pressure near4 (plate layer laminate)) with (dent impression (blind near2 hole) depression via) and metal\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:19

S69	94	S64 and S68	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:23
S70	365	((pressure near4 (plate layer laminate)) with (dent impression (blind near2 hole) depression via)) with metal\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:21
S71	1	S64 and S70	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:20
S72	797	((pressure near4 (plate layer laminate)) with (dent impression (blind near2 hole) depression via)) same metal\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:44
S73	2	S64 and S72	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:21
S74	60952	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:21
S75	5	S72 and S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:22
S76	1520	((pressure near4 (plate layer laminate)) with (dent impression (blind near2 hole) depression via recess)) same metal\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:49

S77	7	S64 and S76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:45
S78	5247	((pressure same (plate layer laminate)) with (dent impression (blind near2 hole) depression via recess)) same metal\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:54
S79	25	S64 and S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:49
S80	1021939	(plate layer laminate surface) with (dent impression (blind near2 hole) depression via recess)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:55
S81	105940	(plate layer laminate surface) with (dent impression (blind near2 hole) depression via recess) same (nozzle chamber)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:57
S82	531	S64 and S81	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:56
S83	56466	(plate layer laminate surface) with (dent impression (blind near2 hole) depression via recess) with (nozzle chamber)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:57
S84	471	S64 and S83	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 10:57

S85	2528	(plate layer laminate surface) with (dent impression (blind near2 hole) depression via recess) with (nozzle chamber) with metal\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:28
S86	27	S64 and S85	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:13
S87	60952	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:27
S88	85017	(plate layer laminate surface) with (dent impression (blind near2 hole) depression via recess) with metal\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:28
S89	86406	(plate layer laminate surface) with (dent impression (blind near2 hole) depression via recess) with (metal\$3 nickel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:14
S90	633	S87 and S89	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:29
S91	311	S90 and piezoelectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:29
S92	1393	(plate layer laminate surface) with (dent impression (blind near2 hole) depression via recess) with (metal\$3 nickel) with (expan\$4 contract\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:31

S93	4	S87 and S92	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:30
S94	12057	(plate layer laminate surface) with (dent impression (blind near2 hole) depression via recess) same (metal\$3 nickel) same (expan\$4 contract\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:31
S95	83	S87 and S94	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 09:06
S96	292	pressure adj chamber adj (layer sheet laminat\$3 surface)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:39
S97	65	S87 and S96	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/31 13:40
S98	736	29/890.1.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:13
S99	5530	347/40,47,56,68-73.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:13
S10 0	1147966	(plate layer surface) with (dent impression (blind near2 hole) depression via recess\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:36

S10 1	80461	(plate layer surface) with (dent impression (blind near2 hole) depression via recess\$3) with (chamber room cavity)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:15
S10 2	623	S99 and S101	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:15
S10 3	4455	(plate layer surface) with (dent impression (blind near2 hole) depression via recess\$3) with (chamber room cavity) with (metal\$3 ni nickel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:18
S10 4	7	S98 and S103	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:16
S10 5	10643	(plate layer surface) with (dent impression (blind near2 hole) depression via recess\$3) with (chamber room cavity) same (metal\$3 ni nickel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:35
S10 6	8	S98 and S105	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:20
S10 7	73	S99 and S105	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:31
S10 8	0	"10644066".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:32

S10 9	4	"644066".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:32
S11 0	36826	(dent impression (blind near2 hole) depression via recess\$3) with (chamber room cavity) same (metal\$3 ni nickel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:35
S11 1	97148	(plate layer surface) with (dent impression (blind near2 hole) depression via recess\$3) with (metal\$3 ni nickel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:37
S11 2	156	S99 and S111	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:36
S11 3	51071	(plate layer surface) with (dent impression (blind near2 hole) depression recess\$3) with (metal\$3 ni nickel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:56
S11 4	62	S99 and S113	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:37
S11 5	5294	(plate layer) with (dent impression (blind near2 hole) depression) with (metal\$3 ni nickel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:57
S11 6	2	S99 and S115	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:57

S11 7	60952	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:58
S11 8	31	S115 and S117	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 08:58
S11 9	2	"6422690".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 09:06
S12 0	12	("3747120" "3946398" "3988745" "4312010" "4353078" "4383264" "4599628" "4825227" "4937597" "5719604" "5757400" "5828394").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/04/01 09:06
S12 1	1	("6422690").URPN.	USPAT	OR	ON	2005/04/01 09:08
S12 2	1	1999-105870.NRAN.	DERWENT	OR	ON	2005/04/01 09:09
S12 3	41345	(ni nickel) with (advantage benefit propert\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 10:13
S12 4	52	S99 and S123	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 10:12
S12 5	124	(ni nickel) with (advantage benefit propert\$3) same piezoelectric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 10:13
S12 6	8	S99 and S125	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/01 10:13